

REMARKS

Claims 1, 2, 5, 7, 8 and 13-20 are pending.

Claims 1, 2, 5, 7, 8 and 13-18 were rejected under 35 USC §103(a) as being unpatentable over Kanda in view of Enoki. Furthermore, claims 19 and 20 were rejected under 35 USC §103(a) as being unpatentable over Kanda in view of Enoki further in view of Ishibashi et al. These rejections are respectfully traversed.

As the Examiner points out, Kanda discloses a coating material which fattens a resist pattern. The coating material of Kanda includes a resin, a surfactant and an organic solvent, but the surfactant of Kanda is different from those set forth in the present claims. The Examiner cites Enoki and states that Enoki discloses surfactants of the subject application.

According to Claim 1 of Enoki, a resin composition of Enoki is for insulating material, including as essential components:

(A) a compound having an amphipathic property, and

(B) a heat-resistant resin having a glass transition temperature higher than a thermal decomposition temperature of the compound (A), or a precursor thereof.

Enoki gives numerous examples for the component (A), which include surfactants set forth in the claims of the present application (col. 2, line 63 to col. 3, line 30).

Enoki's resin (B) in the resin composition is a heat-resistant resin having a glass transition temperature higher than a thermal decomposition temperature of the compound having an amphipathic property, examples thereof including a polyimide resin and polyamic acid (col. 4,

line 43). This indicates that Enoki's heat-resistant resin is not water-soluble but alkali-soluble. Water should not be included in the resin composition of Enoki because the resin composition of Enoki is for an insulating material. Furthermore, see col. 4, lines 54-67 of Enoki which discuss suitable solvents for its insulating material, which do not include water.

The resist pattern thickening material of the subject application includes water as an essential component. Kanda's coating material is an aqueous resin composition including a water-soluble resin, a crosslinking agent and a surfactant (paragraph [0013]). Kanda's exemplary resins are water-soluble resins, and Kanda does not disclose water-insoluble resins such as polyimide resin.

Accordingly, one of ordinary skill in the art would not have been motivated to combine the teachings of Kanda and Enoki in a manner suggested by the Examiner. There would have been no motivation to consider the surfactants taught by Enoki in the composition of Kanda. As such, the combination of references would not suggest the claimed invention.

Ishibashi et al. fails to provide the teachings which Kanda and Enoki lack.

For at least the foregoing reasons, the claimed invention distinguishes over the cited art and defines patentable subject matter. Favorable reconsideration is respectfully requested.

Should the Examiner deem that any further action by applicants would be desirable to place the application in condition for allowance, the Examiner is encouraged to telephone applicants' undersigned attorney.

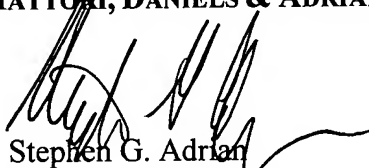
Application No.: 10/670,291
Art Unit: 1756

Request for Reconsideration
Attorney Docket No.: 031181

If this paper is not timely filed, Applicants respectfully petition for an appropriate extension of time. The fees for such an extension or any other fees that may be due with respect to this paper may be charged to Deposit Account No. 50-2866.

Respectfully submitted,

WESTERMAN, HATTORI, DANIELS & ADRIAN, LLP

A handwritten signature in black ink, appearing to read 'Stephen G. Adrian', is written over the printed name.

Stephen G. Adrian
Attorney for Applicants
Registration No. 32,878
Telephone: (202) 822-1100
Facsimile: (202) 822-1111

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